# Are interfaces good or bad for thermal management? Mediocre carbon nanotube composites and ultra-low thermal conductivity solids

#### Pawel Keblinski

Materials Science and Engineering Department Rensselaer Polytechnic Institute

Work Supported by NSF under DMR 134725 and U.S. Department of Energy, Office of Science under Contract W-31-109-Eng-38

Coworkers

```
David Cahill (University of Illinois Urbana)
Ravi Prasher (Intel, Phoenix, AZ)
Fabrizio Cleri, Lille, France
Rahmi Ozisik (RPI)
Graduate students: Liping Xue, Nantalia Shenogina,
Arun Bodapati, Lin Hu
```

Postdoctoral researcher: Sergei Shenogin

# **Carbon Nanotube Composites** The best fiber spoiled by the interface

# Carbon Nanotube Composites and Transport



#### Carbon Nanotubes

- Pure (defect free) are excellent heat conductors (3000 W/mK) and depending on the tube chirality may be electrically conductive or semiconductive
- Yery high aspect ratio fibers (~1000) should lead to a great enhancement of composite thermal and electrical conductivity at low volume fraction, due to low percolation threshold
- Experimental results do not confirm all of these these predictions. For example, thermal conductivity increase is significant, but not as high as expected.

# Fibers and Percolation

• When a continuous path along the carbon nanotubes is created, i.e. the percolation threshold is exceeded, a sharp increase in transport characteristics is expected

 To percolate each fiber has to be, on average, in contact with ~ 2+ other fibers.

- At the percolation threshold: Number of contacts/fiber ~ L V<sub>fiber</sub>
   ~ constant
- → V<sub>c</sub> ~ 1 / L the percolation threshold proportional to the inverse of the aspect ratio
- ➔ For spheres V<sub>c</sub> ~ 30% volume, for carbon nanotube composites V<sub>c</sub> can be of the order of 0.1%



# Conductivity Matrix vs. Fiber

Thermal conductivity W/m-K 10 100 1000 YSZ Alumina **D** i amond Isotropic copper CN polymers **Phonons Phonons** electrons Phonons Electrical 10<sup>15</sup> – electrical conductivity σ<sub>conductor</sub> conductivity Cu -  $\sigma$ = 5 10<sup>5</sup> ( $\Omega$ cm)<sup>-1</sup>  $\sigma_{insulator}$  $10^4$  – thermal diamond -  $\sigma = 10^{-10}$ conductivity  $(\Omega \text{cm})^{-1}$ 

## Electrical Transport - Puzzle # 1

• Percolation threshold, V<sub>c</sub>, is 0.3% - indeed very low

• Above the percolation threshold conductivity,  $\sigma$ , exhibit universal scaling  $\sigma \sim (V - V_c)^{\circ}$ 

with  $\alpha \approx 2$  - just percolation in 3 dimensions

• But why the percolation threshold scaling law holds up to

$$\frac{V}{V_{c}} = 100 ?!$$

Electric transport properties and percolation in carbon nanotubes / PMMA composites



J-M Benoit, at. al. Mat. Res. Soc. Symp. Proc. Vol. 706 (2002)

#### Simple Rule of Mixtures for Thermal Conductivity



fifty-fold

<u>increase!!</u>

## Thermal Transport Puzzle # 2

• Actual increase at 1% volume fraction is only 2-3 fold rather than 50 fold

- Nothing special happens at the percolation threshold
- Thermal conductivity increases are non-linear in fiber volume ₱r 80% \$\$\$\$ a le explanations
  - → Intrinsic tube conductivity compromised by defects
  - -> Interrace.



S-U. Choi, at al., Appl. Phys. Lett. 79, 2252-2254 (2001).

Interfacial resistance 
$$\longrightarrow J_Q = \sigma_K \Delta T$$
  
of the tube-matrix

# Nanotube – Matrix Heat Transfer: Simulation

Constant flux simulations

1. Pour the heat to the tube and remove from the liquid

2. Monitor the temperature profile

Constant heat flux  $5 \times 10^{-8}$  W; heat sink from L = 18 to L = 20 Å





$$\sigma_{\rm K} = \frac{J_Q}{\Delta T} = \frac{dQ/dt}{A\Delta T}$$

- Most of the temperature drop at the interface
- Interfacial conductance,  $\sigma_{K} \sim 25 \text{ M W/K-m}^{2}$



- Relaxation time ~ 40-70 ps
- Interfacial conductance,  $\sigma_{K} \sim 10-20 \text{ M W/K-m}^{2}$



Liquid has low frequency modes associated with weak dispersion forces between liquid molecules. The same forces act between liquid and nanotube walls
Carbon nanotubes have a small number of low frequency modes associated with bending and squeezing. Only these modes can couple strongly with liquid.

Weak harmonic coupling between liquid and carbon nanotubes leads to large thermal interfacial resistance - the same for nanotube-polymer composites

## Mechanism of the Heat Flow



• Only few low frequency bending modes are effective in coupling with liquid

## So What About Nanotube Based Composites?

 Equivalent matrix thickness interfacial resistance,  $h_{M}$ , is defined as the thickness of the matrix over which the temperature drop is the same as the temperature drop at the interface.  $h = \frac{\text{matrix conductivity}}{\text{int erfacial conductivity}} = \frac{k}{\sigma_{K}}$ • For interfacial conductance,  $\sigma_{k}$  = ~1.0 x 10^7 W/K-m^{2} and low conductivity matrix, k= 0.2 W/K-m  $h_{\rm M} = 20 \, \rm nm$ In CN composites, interfacial resistance plays • Equivalent tube length,  $h_{cNT}$  (k= 3000 W/K-m)  $h_{CNT} \sim 0.3 \text{ mm}$ a major role in determining effective heat flow

## Chemical Functionalization



# Net Effect on Composite Conductivity



 For tube length comparable with L<sub>c</sub>, composite conductivity can be improved by chemical functionalization

#### Conductivity on Percolating Tube



- Near the percolation threshold for both mechanisms  $\mu V^{\sim}$   $(V-V_c)^2$
- For bulk resistance above ~ V = 2V\_c,  $\sigma$  ~ V
- For contact resistance percolation threshold power law appears to persist

# Electrical vs. Thermal Percolation

- At macroscopic level thermal and electrical transport are described by the same equations.
- For example in the steady state temperature satisfied the Laplace Equation

 $\Delta T = 0$ 

 The flux continuity condition at the matrix-fiber interface

$$-J_{\mathcal{Q}} = k_m \frac{\partial T_m}{\partial \mathbf{n}} = k_f \frac{\partial T_f}{\partial \mathbf{n}}$$

 The electrical transport is described by the same equations, T is replaced with potential and thermal conductivity with electrical conductivity

# Finite Element Calculations

 Heat flow between two fibers



- Ends of one fiber kept at higher temperature than the other - the rest of boundaries are adiabatic (no heat flux across the interface )

#### Heat Flow Rate vs. Tube separation



- Relatively small fiber to matrix conductivity ratio and interfacial thermal resistance completely eliminates the effect of fiber-fiber contacts
- •For the electrical conductivity problem larger ratio of fiber to matrix conductivity leads to electrical percolation

# Ultra-low Thermal Conductivity of Layered Materials

#### Below the amorphous material limit



- Grain boundaries ?

C. Chiritescu, D. G. Cahill, et al., Science. 315, 353(2007).





#### A B A B A B A B A B

QuickTime<sup>™</sup> and a TIFF (Uncompressed) decompressor are needed to see this picture.

Perfect crystal

#### A C A B C B A B A B

QuickTime™ and a TIFF (Uncompressed) decompressor are needed to see this picture.

Stacking disorder

QuickTime<sup>™</sup> and a TIFF (Uncompressed) decompressor are needed to see this picture. Grain boundaries

Mass disorder

QuickTime™ and a TIFF (Uncompressed) decompre₅ are needed to see this picture.



#### Model interactions

#### Lennard-Jones potential

$$U(r) = 4\varepsilon \left[ \left(\frac{\sigma}{r}\right)^{12} - \left(\frac{\sigma}{r}\right)^{6} \right]$$



Harmonic springs



Two sets of  $\epsilon$  and  $\sigma$  parameters are used

- Within WSe<sub>2</sub> sheet:  $\epsilon$  = 0.455 eV and  $\sigma$  = 2.31 Å
- Between layers:  $\epsilon$  = 0.04 eV and  $\sigma$  = 3.4 Å



#### Molecular dynamics results

QuickTime<sup>™</sup> and a TIFF (Uncompressed) decompressor are needed to see this picture.

Perfect crystal and stacking disordered structures show strong film thickness dependence not observed in experiment

Structures with grain boundaries show lower conductivity and weaker size dependence



**Perfect crystal** 

 Low frequency phonons are delocalized and polarized

QuickTime™ and a TIFF (Uncompressed) decompressor are needed to see this picture.

> Higher frequency phonons are delocalized but not well polarized



**Stacking disorder** 

Low frequency phonons are delocalized and polarized, same way as in perfect crystal

QuickTime<sup>™</sup> and a TIFF (Uncompressed) decompressor are needed to see this picture.

Higher frequency
 phonons can be localized
 or delocalized but they
 do not matter much for
 thermal transport



Grain boundary

QuickTime<sup>™</sup> and a TIFF (Uncompressed) decompressor are needed to see this picture.  Low frequency phonons are weakly localized and weakly polarized

Conductivity reduction and weak size dependence

 Higher frequency phonons can be localized or not and are not polarized



Mass disorder

Even low frequency modes are localized

QuickTime™ and a TIFF (Uncompressed) decompressor are needed to see this picture. Ultimate conductivity reduction and essentially no size dependence

Thermal conductivity of a dense solid below that of still air



#### Interfacial Perspective

Interfacial conductance from relaxation and equilibrium simulations

Effective conductivity  $\kappa = Gxd$ 

QuickTime™ and a TIFF (Uncompressed) decompressor are needed to see this picture.

QuickTime™ and a TIFF (Uncompressed) decompressor are needed to see this picture. d=1nm - grain boundary size

 $G \approx 25 \text{ MW/m}^2\text{-K}$ 

 $\kappa \approx 0.025 \ W/m\text{-}K$ 

Actual conductivity

 $\kappa \approx 0.05 \ W/m\text{-}K$ 

Collective aspect of the vibrational heat transfer is responsible for the difference



Stacking disordered is insufficient to lead to ultra-low thermal conductivity which is due to the fact that low frequency phonons are still polarized and carry heat over large distances

Nanostructuring (introduction of grain boundaries) depolarize and partially localize phonons leading to amorphous-like thermal transport and ultra-low thermal conductivity which can be also understood in terms of the interfacial thermal resistance.

Introducing mass disorder leads to complete localization of phonons and further reduction of thermal conductivity to level below that of conductivity of still air.

